

Features

- Epitaxial Planar Die Construction
- Ideal for Low Power Amplification and Switching
- Complementary NPN Type Available (DSS8110Y)
- Ultra Small Surface Mount Package
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free "Green" Device (Note 2)
- ESD rating: 400V-MM, 8KV-HBM

Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.006 grams (approximate)

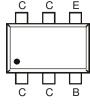


Top View



С

Device Symbol



Top View Pin Out Configuration

Ordering Information (Note 3)

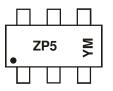
Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DSS9110Y-7	ZP5	7	8mm	3,000

Notes: 1. No purposefully added lead.

2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com

3. For packaging details, go to our website at http://www.diodes.com

Marking Information



ZP5 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: V = 2008) M = Month (ex: 9 = September)

Date Code Key												
Year	2010		2011	2012		2013	2014		2015	2016		2017
Code	Х		Y	Z		А	В		С	D		E
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



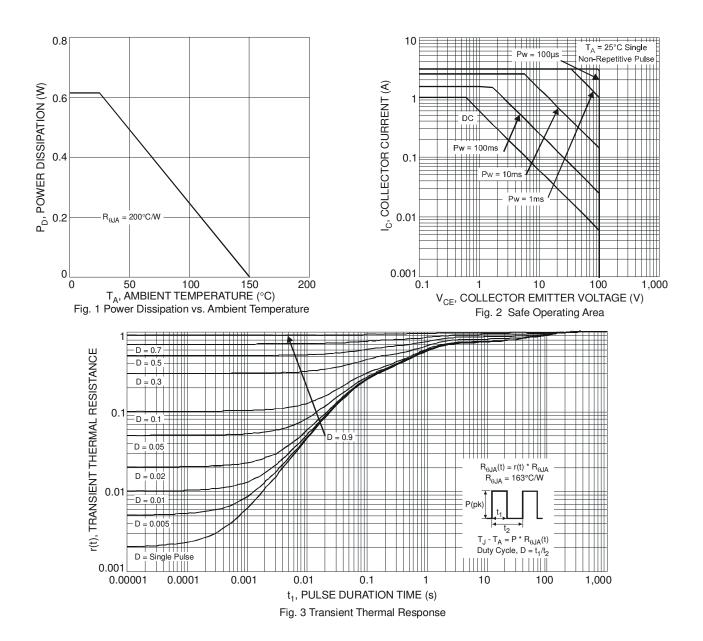
Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-120	V
Collector-Emitter Voltage	V _{CEO}	-100	V
Emitter-Base Voltage	V _{EBO}	-5	V
Collector Current - Continuous	lc	-1	A
Peak Pulse Collector Current	I _{CM}	-3	A
Base Current – Continuous	IB	-0.3	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4) @ $T_A = 25^{\circ}C$	PD	625	mW
Thermal Resistance, Junction to Ambient (Note 4) @ $T_A = 25^{\circ}C$	$R_{\theta JA}$	200	°C/W
Operating and Storage Temperature Range	TJ, T _{STG}	-55 to +150	O°

Notes: 4. Device mounted on FR-4 PCB, with minimum recommended pad layout.

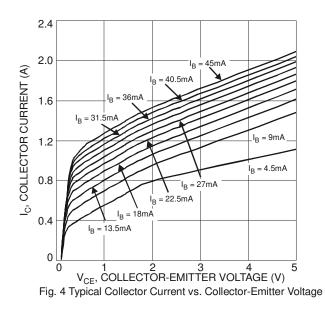


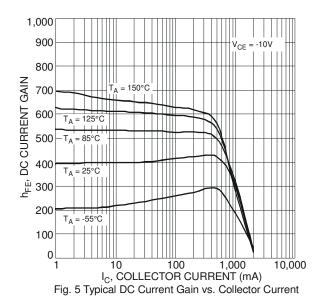


Electrical Characteristics @T_A = 25°C unless otherwise specified

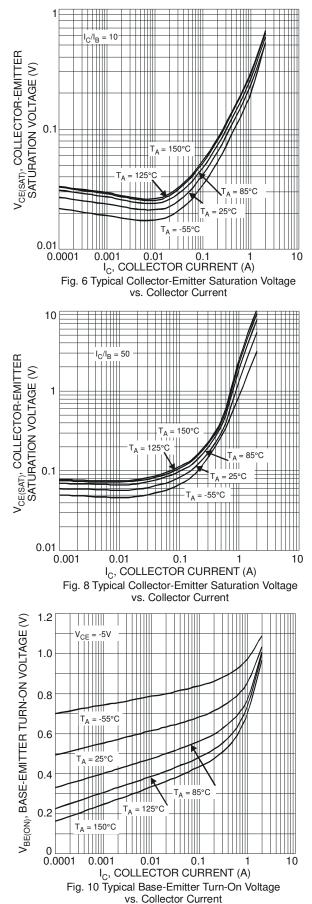
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-120	—	—	V	$I_{C} = -100 \mu A, I_{E} = 0$
Collector-Emitter Breakdown Voltage (Note 5)	BV _{CEO}	-100			V	$I_{\rm C} = -10 {\rm mA}, \ I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	-5	_		V	$I_E = -100 \mu A, I_C = 0$
Collector Cutoff Current	1000	_	_	-100	nA	$V_{CB} = -80V, I_E = 0$
	I _{CBO}			-50	μA	$V_{CB} = -80V, I_E = 0, T_A = 150^{\circ}C$
Collector Cutoff Current	ICES			-100	nA	$V_{CE} = -80V, V_{BE} = 0$
Emitter Cutoff Current	I _{EBO}	—	—	-100	nA	$V_{EB} = -4V, \ I_C = 0$
		150			V	$V_{CE} = -5V, I_{C} = -1mA$
DC Current Gain (Note 5)	h _{FE}	150	—			$V_{CE} = -5V, I_{C} = -250mA$
	UFE	150	—	450		$V_{CE} = -5V, I_C = -500mA$
		125	—			$V_{CE} = -5V, I_C = -1A$
	V _{CE(sat)}	_	_	-120		I _C = -250mA, I _B = -25mA
Collector-Emitter Saturation Voltage (Note 5)			—	-180		I _C = -500mA, I _B = -50mA
				-320		$I_{C} = -1A, I_{B} = -100mA$
Collector-Emitter Saturation Resistance	R _{CE(sat)}	_	_	320	mΩ	$I_{C} = -1A, I_{B} = -100mA$
Base-Emitter Saturation Voltage	V _{BE(sat)}	_	_	-1.1	V	I _C = -1A, I _B = -100mA
Base-Emitter Turn On Voltage	V _{BE(on)}	_		-1	V	$V_{CE} = -5V, I_{C} = -1A$
Output Capacitance	C _{obo}		16		pF	V _{CB} = -10V, f = 1.0MHz
Current Gain-Bandwidth Product	f _T	100	_		MHz	V _{CE} = -10V, I _C = -50mA, f = 100MHz
Delay Time	t _d		27		ns	
Rise Time	tr		230	_	ns	$V_{\rm CC} = -10V, I_{\rm C} = -1A,$
Storage Time	ts		165		ns	$I_{B1} = -I_{B2} = -50 \text{mA}$
Fall Time	t _f		160		ns	

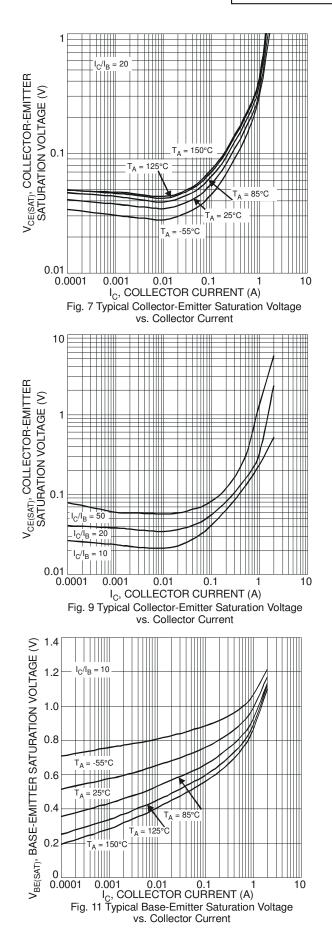
Notes: 5. Measured under pulsed conditions. Pulse width = $300\mu s$. Duty cycle $\leq 2\%$.





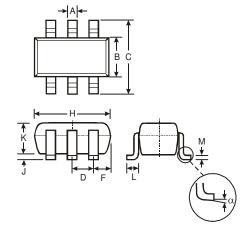






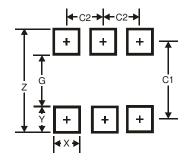


Package Outline Dimensions



SOT-363						
Dim	Min	Max				
Α	0.10	0.30				
В	1.15	1.35				
C	2.00	2.20				
D	0.65 Typ					
F	0.40	0.45				
Н	1.80	2.20				
J	0	0.10				
К	0.90	1.00				
L	0.25	0.40				
М	0.10	0.22				
α	0°	8°				
All Di	All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65



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